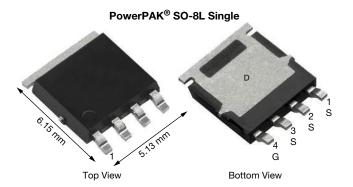
SQJ444EP

www.vishay.com

Vishay Siliconix

Automotive N-Channel 40 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY	
V _{DS} (V)	40
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 V$	0.0032
$R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$	0.0043
I _D (A)	60
Configuration	Single

FEATURES

- TrenchFET[®] power MOSFET
- AEC-Q101 qualified
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

N-Channel MOSFET



ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJ444EP (for detailed order number please see <u>www.vishay.com/doc?79771</u>)

ABSOLUTE MAXIMUM RATING	S (T _C = 25 °C, unless	otherwise noted	l)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	40	V	
Gate-source voltage		V _{GS}	± 20		
Continuous drain current ^a	T _C = 25 °C	I-	60		
	T _C = 125 °C	Ι _D	60		
Continuous source current (diode conduction) ^a		ا _S	60	А	
Pulsed drain current ^b		I _{DM}	150		
Single pulse avalanche current	L = 0.1 mH	I _{AS}	25		
Single pulse avalanche energy	L = 0.1 IIIA	E _{AS}	31.2	mJ	
Maximum power dissipation ^b	$T_{\rm C} = 25 ^{\circ}{\rm C}$	Pn	68	W	
	T _C = 125 °C	FD	22	vv	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) ^{d, e}		-	260	U	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction to ambient	PCB mount ^c	R _{thJA}	68	°C/W
Junction to case (drain)		R _{thJC}	2.2	C/W

Notes

- a. Package limited
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %
- c. When mounted on 1" square Pcb (Fr4 material)
- d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

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Vishay			11.
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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static	•	-				<u> </u>	
Drain-source breakdown voltage	V _{DS}	V _{GS}	= 0, I _D = 250 μA	40	-	-	v
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	1.5	2.0	2.5	v
Gate-source leakage	I _{GSS}	V _{DS} =	0 V, V_{GS} = ± 20 V	-	-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 40 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	$V_{GS} = 0 V$	V_{DS} = 40 V, T_J = 125 °C	-	-	50	μA
		$V_{GS} = 0 V$	$V_{DS}=40~V,~T_J=175~^\circ C$	-	-	250	
On-state drain current ^a	I _{D(on)}	$V_{GS} = 10 V$	$V_{DS} \ge 5 V$	30	-	-	А
		$V_{GS} = 10 V$	I _D = 10 A	-	0.0026	0.0032	
Drain course on state registence à	В	$V_{GS} = 4.5 \text{ V}$	I _D = 8 A	-	0.0034	0.0043	Ω
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 10 A, T _J = 125 °C	-	-	0.0048	52
		V _{GS} = 10 V	I _D = 10 A, T _J = 175 °C	-	-	0.0057	
Forward transconductance b	9 fs	$V_{DS} = 15 \text{ V}, I_D = 10 \text{ A}$		-	80	-	S
Dynamic ^b							
Input capacitance	C _{iss}			-	3700	5000	
Output capacitance	C _{oss}	$V_{GS} = 0 V$	$V_{DS} = 25 V$, f = 1 MHz	-	2310	3050	pF
Reverse transfer capacitance	C _{rss}			-	160	220	
Total gate charge ^c	Qg			-	51	80	
Gate-source charge ^c	Q _{gs}	$V_{GS} = 10 \text{ V}$	$V_{DS}=20~V,~I_{D}=5~A$	-	9	-	nC
Gate-drain charge ^c	Q _{gd}			-	7	-	
Gate resistance	R _g	f = 1 MHz		0.20	0.44	0.70	Ω
Turn-on delay time ^c	t _{d(on)}			-	11	20	
Rise time ^c	t _r	00	$V_{DD} = 20 \text{ V}, \text{ R}_{L} = 4 \Omega$		19	30]
Turn-off delay time ^c	t _{d(off)}	$I_D \cong 5 A, T$	V_{GEN} = 10 V, R_g = 1 Ω	-	30	50	ns
Fall time ^c	t _f			-	21	35	
Source-Drain Diode Ratings and Char	racteristics ^b						
Pulsed current ^a	I _{SM}			-	-	150	А
Forward voltage	V _{SD}	le :	= 15 A, V _{GS} = 0	-	0.8	1.2	V

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

b. Guaranteed by design, not subject to production testing

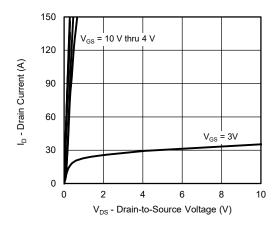
c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

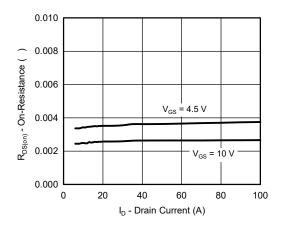
2



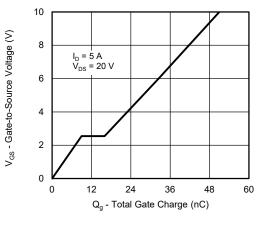
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



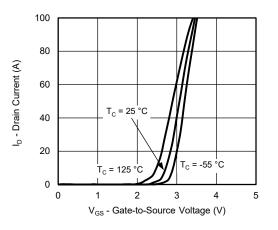
Output Characteristics



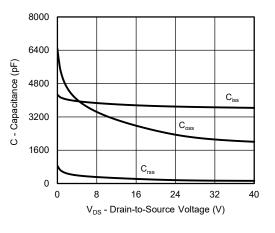
On-Resistance vs. Drain Current



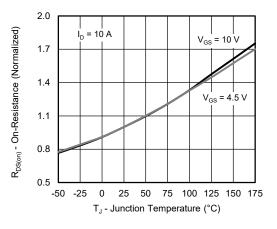
Gate Charge



Transfer Characteristics



Capacitance



On-Resistance vs. Junction Temperature

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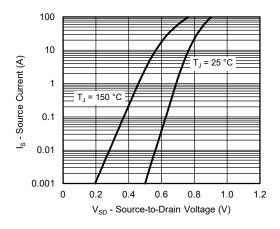
3

Document Number: 75858

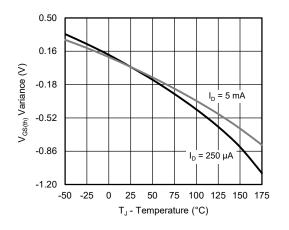
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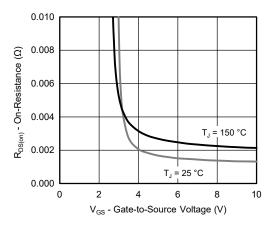
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



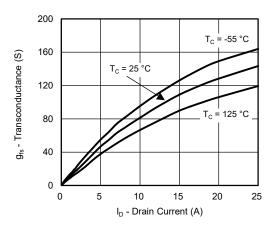
Source Drain Diode Forward Voltage



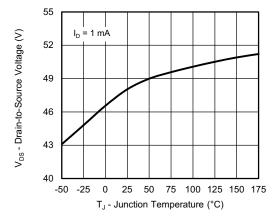
Threshold Voltage



On-Resistance vs. Gate-to Source Voltage



Transconductance



Drain Source Breakdown vs. Junction Temperature

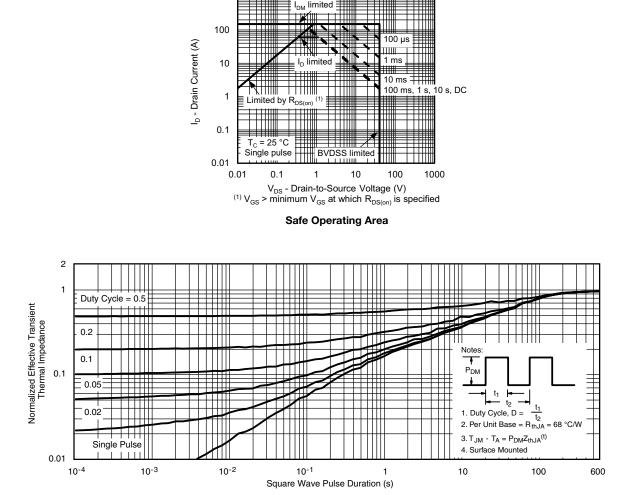
4

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TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)

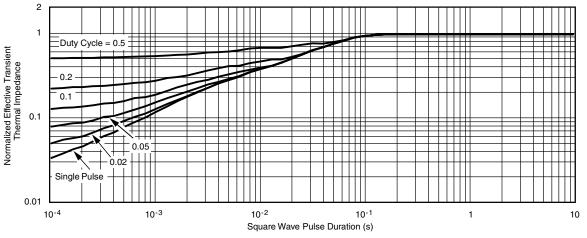
1000



Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

• The characteristics shown in the two graphs

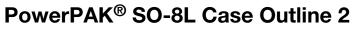
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

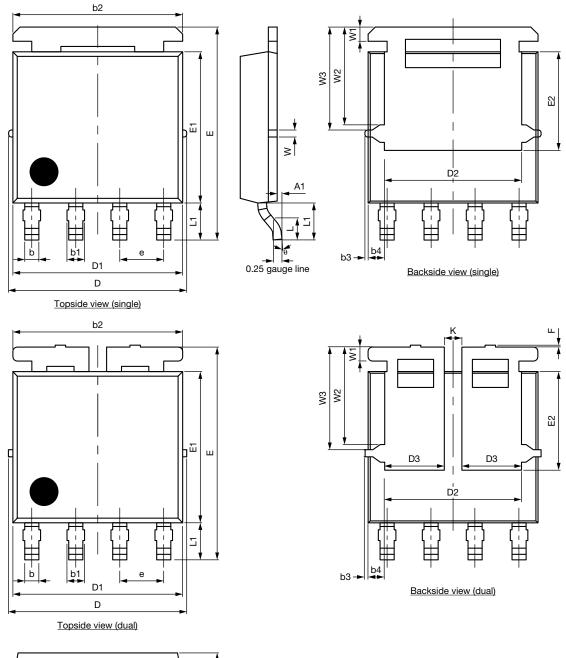
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

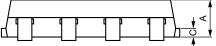
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?75858.









1 For technical questions, contact: <u>pmostechsupport@vishay.com</u>

Package Information



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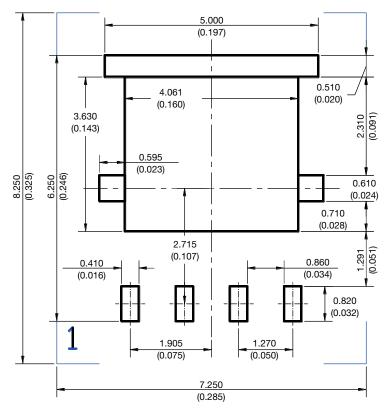
DIM.	MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
К		0.51			0.020		
W		0.23			0.009		
W1	0.41			0.016			
W2	2.82			0.111			
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

Note

• Millimeters will govern



RECOMMENDED MINIMUM PAD FOR PowerPAK[®] SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)

Revision: 07-Feb-12



Vishay

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